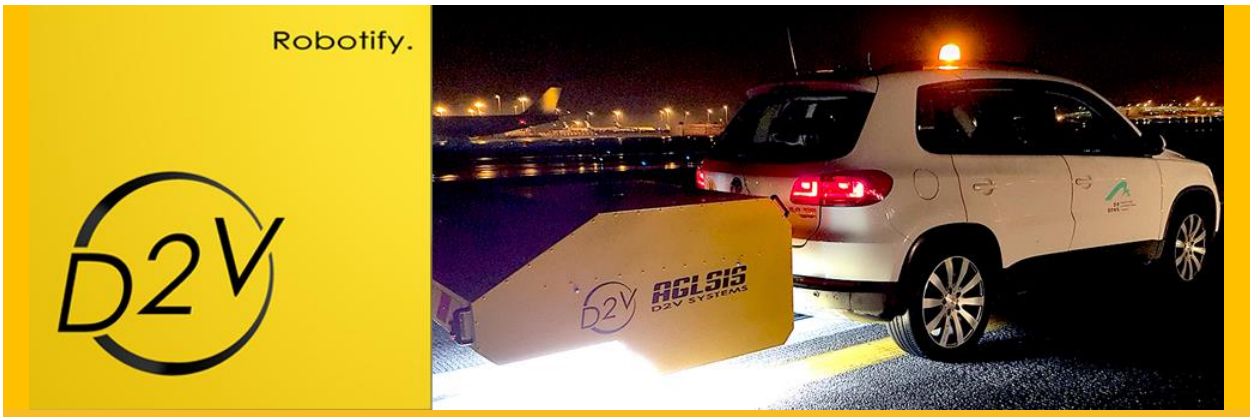

Technology Analyst (Student Intern)

Ref: TAT-INTERN-2019

Job Description

We look for high-caliber candidates for the followings: -

Target Candidate:

This position is open to graduate.

Responsibilities

- Conduct in-depth engineering analysis according to design specifications
- Software stream: Assist in system design, implementation and testing work which may include computer programming, mobile apps design for IoT/Big Data application
- Mechanical stream: Assist in system design, implementation and testing work related to mechanical, automation and actuation design

Salary

- Competitive

Skills & Requirements

- Graduation Year: 2020 onward
- Fields of Study: **Computer & Information Sciences, Electrical and Computer Engineering, Mechanical Engineering, Engineering**
- Education Level: **Bachelor degree student**
- Required Level of Work Experience: Prefer experience from ROBOCON, ROV or participation in Robotics Team

Technical Requirements

- Familiar with at least one computer language
- Familiar with OpenCV or Point Cloud Library
- Familiar with software development & management tools e.g. Git
- Engineer and detailed mind set
- Attention to details

Qualification Requirements

- Degree holder in Computer Science / Computer Engineering / Information Technology
- Possess strong problem-solving skills and is able to work independently
- Excellent communication skills in English or Cantonese
- Candidates who are immediately available or with short notice will be considered first

About D2V Limited

D2V is a technological start-up company who designs top-tier A.I.-assisted automation systems for industrial applications in different sectors, including logistics, mass transportation, and safety critical infrastructure. Our A.I. processing soft core extends the functionality and fidelity of existing mechatronics systems.

Our product and service won the
- Bronze Award in the Best Smart Hong Kong Award (Open Data / Big Data Application) of the Hong Kong Information and Communications Technology (ICT) Awards 2017
- Champion of the Hong Kong Electronics Project Competition 2017, organized by the Electronics Division of the Hong Kong Institute of Engineers.
- The Winner of International Airport Award (Airside Operation) 2017, organized by the International Airport Review

Application Methods

Please address your application to: Dr. Nick Lau

E-mail: info@d2v.hk
Link: http://www.d2v.hk
Directions Unit 309A, 3/F, Core Building 1, 1 Science Park East Avenue, Science Park, Shatin, NT, Hong Kong
Telephone (852) 59138980
Fax (852) 30078970

Note:
Interested parties please apply directly by submitting your CV and student card, transcript in PDF format. Only potential applicants will be contacted. For any inquiry, please contact via info@d2v.hk or +852 5913 8980.

Personal Information Collection Statement (PICS)

The personal data provided by means of the application form will be used by the relevant parties for the purpose of processing your application to assess your suitability for the position you are applying for.

When you provide personal data to us, please make sure that the data are accurate and complete. If you fail to provide us with the information required or if the information provided is inaccurate or incomplete, your prospective employment/employment with D2V Limited (the "D2V") will be affected.

Please also note that your personal data may be made available to:

- appropriate persons in D2V;
- any other relevant parties who require them for matters related to your employment with or generally in respect of your provisions of services to D2V;
- any relevant government departments/appropriate authorities when D2V is required to provide them under the relevant legislation for use for the purpose of that legislation; or
- where permitted or authorized by law.
- We will obtain your consent before using your personal data for any other purposes.

If you wish to request for access to and/or correction of your personal data, you may do so under the Personal Data (Privacy) Ordinance. Such request should be made in writing and addressed to D2V at Unit 309A, 3/F, Core Building 1, No. 1 Science Park East Avenue, Science Park, Shatin, NT, Hong Kong, or by e-mail info@d2v.hk